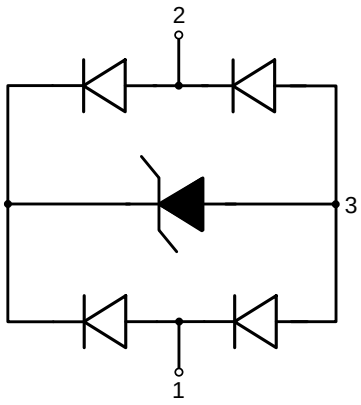
Features

- Stand-off voltage: 5V max.
- Transient protection for each line according to
  IEC61000-4-2 (ESD): ±20kV (contact and air discharge)
  IEC61000-4-4 (EFT): 40A (5/50ns)
  IEC61000-4-5 (surge): 4A (8/20μs)
- Ultra-low capacitance: C_J = 0.4pF typ.
- Ultra-low leakage current: I_R <1nA typ.
- Low clamping voltage: V_{CL} = 14V @ I_{PP} = 16A(TLP)
- Solid-state silicon technology

DFN1006-3L (Bottom View)



Circuit diagram

Applications

- USB 2.0 and USB 3.0
- HDMI 1.3 and HDMI 1.4
- SATA and eSATA
- DVI
- IEEE 1394
- PCI Express
- Portable Electronics and Notebooks

Absolute maximum ratings

Parameter	Symbol	Rating	Unit
Peak pulse power (t_p = 8/20μs)	P_{pk}	56	W
Peak pulse current (t_p = 8/20μs)	I_{PP}	4	A
ESD according to IEC61000-4-2 air discharge	V_{ESD}	±20	kV
ESD according to IEC61000-4-2 contact discharge		±20	
Junction temperature	T_J	125	°C
Operating temperature	T_{OP}	-40~85	°C
Lead temperature	T_L	260	°C
Storage temperature	T_{STG}	-55~150	°C

Electrical characteristics (T_A = 25 °C, unless otherwise noted)

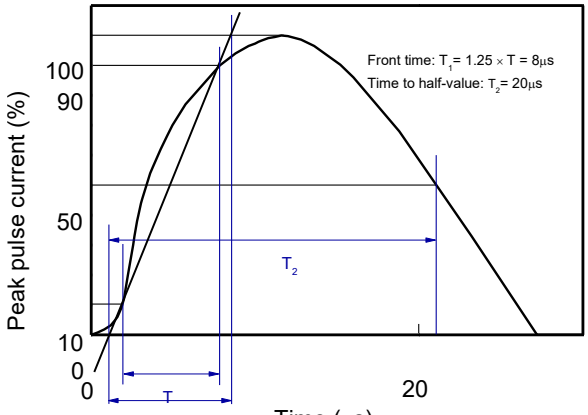
Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Reverse maximum working voltage	V_{RWM}				5.0	V
Reverse leakage current	I_R	V_{RWM} = 5V		<1	100	nA
Reverse breakdown voltage	V_{BR}	I_T = 1mA	7.0	8.0	9.0	V
Forward voltage	V_F	I_T = 10mA	0.6	0.9	1.2	V
Clamping voltage *1)*	V_{CL}	I_{PP} = 16A, t_p = 100ns		14.0		V
Dynamic resistance *1)*	R_{DYN}			0.35		Ω
Clamping voltage *2)*	V_{CL}	I_{PP} = 1A, t_p = 8/20μs			11	V
		I_{PP} = 4A, t_p = 8/20μs			14	V
Junction capacitance	C_J	V_R = 0V, f = 1MHz Pin1 or 2 to Pin3		0.40	0.65	pF
		V_R = 0V, f = 1MHz Between Pin1 and Pin2		0.25	0.40	pF

Notes:

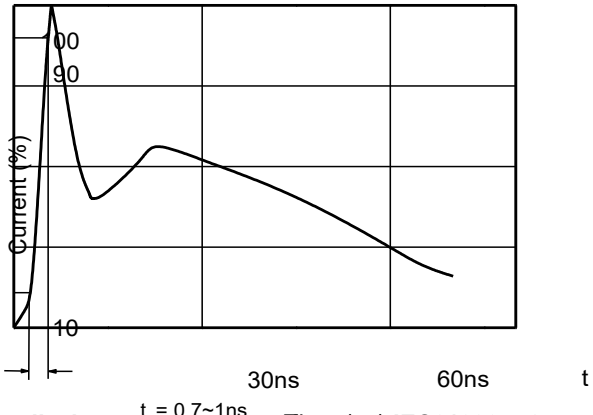
1) TLP parameter: Z_0 = 50 Ω , t_p = 100ns, t_r = 2ns, averaging window from 60ns to 80ns. R_{DYN} is calculated from 4A to 16A.

2) Non-repetitive current pulse, according to IEC61000-4-5.

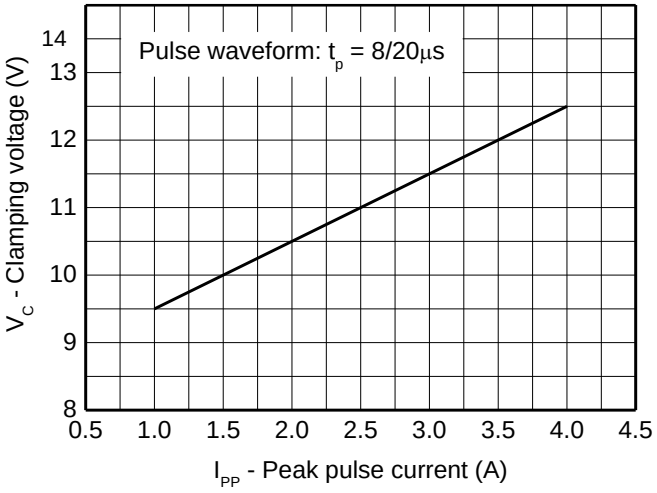
Typical characteristics (T_A = 25 °C, unless otherwise noted)



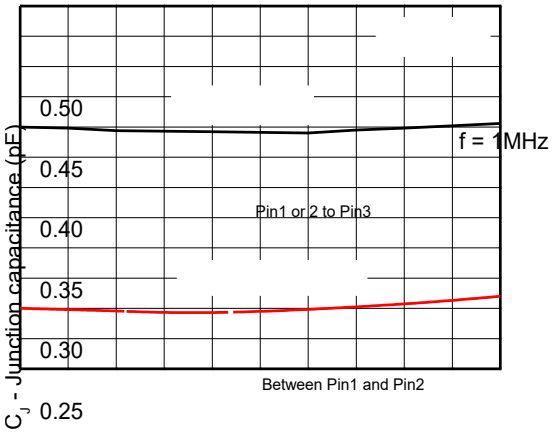
8/20μs waveform per IEC61000-4-5



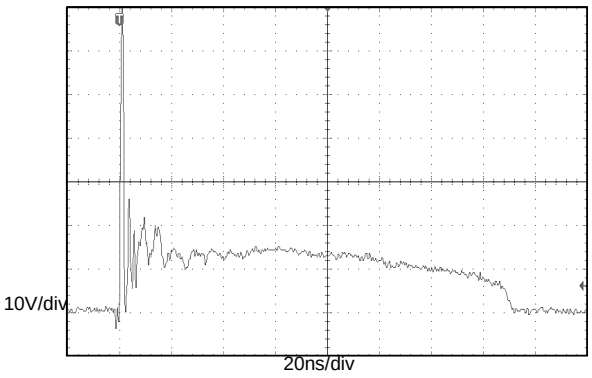
Contact discharge current waveform per IEC61000-4-2



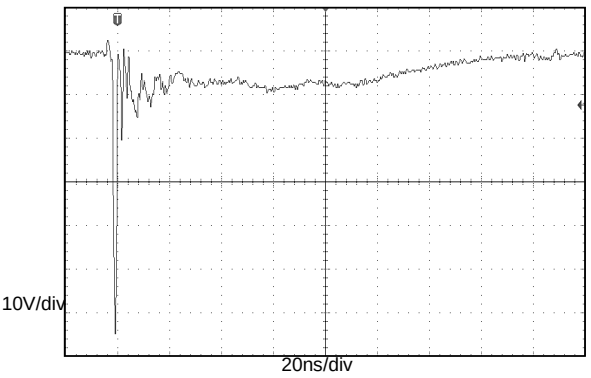
Clamping voltage vs. Peak pulse current



Capacitance vs. Reverse voltage

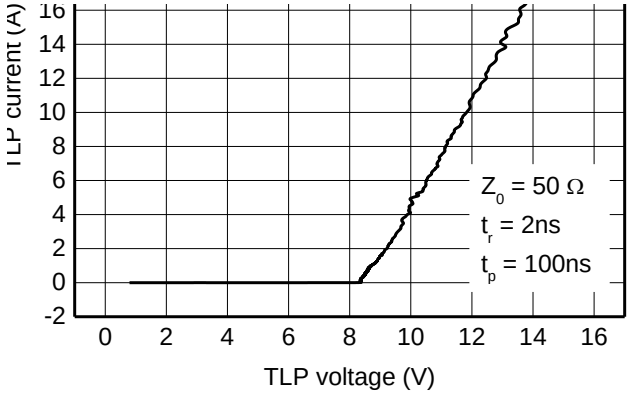


ESD clamping
(+8kV contact discharge per IEC61000-4-2)



ESD clamping
(-8kV contact discharge per IEC61000-4-2)

Typical characteristics (T_A = 25 °C, unless otherwise noted)



TLP Measurement

Application Information

The ESD5302N is designed to protect two high speed line against ESD. Fig1 is shown the connection and Fig2 is shown PCB Layout guide for USB interface ESD protection

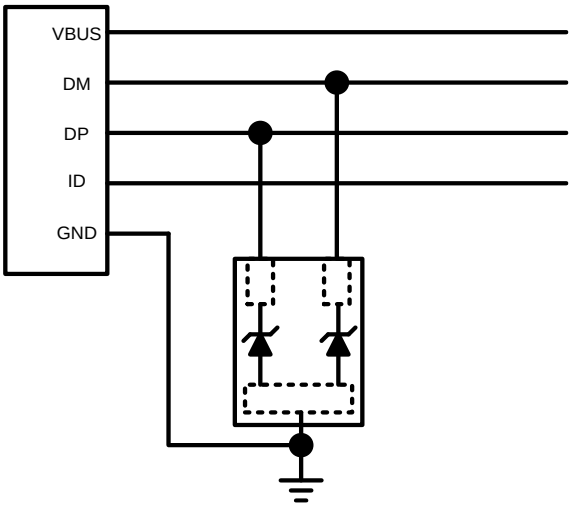


Fig1

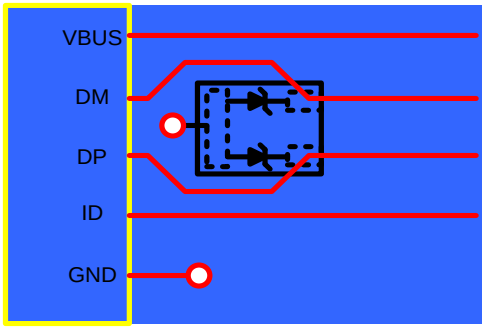
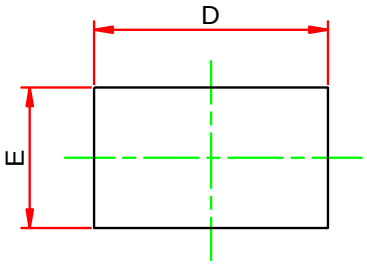


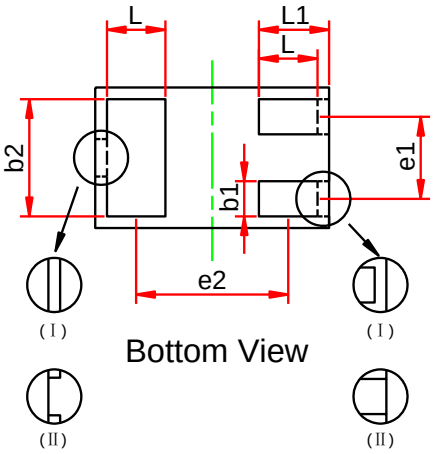
Fig2

PACKAGE OUTLINE DIMENSIONS

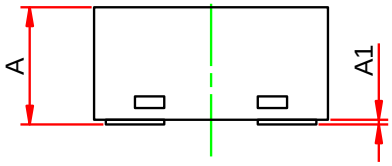
DFN1006-3L



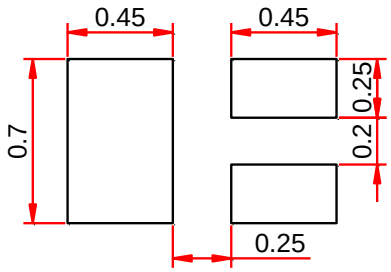
Top View



Bottom View



Side View



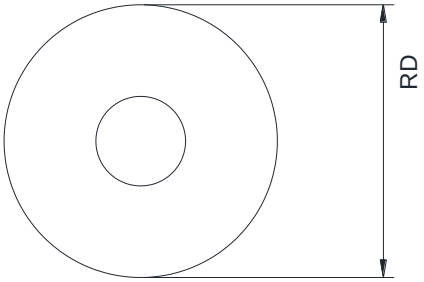
RECOMMENDED LAND PATTERN(Unit:mm)

Symbol	Dimensions in Millimeters		
	Min.	Typ.	Max.
A	0.36	-	0.50
A1	0.00	-	0.05
D	0.95	1.00	1.05
E	0.55	0.60	0.65
b1	0.10	0.15	0.20
b2	0.40	0.50	0.60
L	0.20	0.25	0.30
L1	0.20	0.30	0.40
e1	0.35Ref		
e2	0.65 Ref		

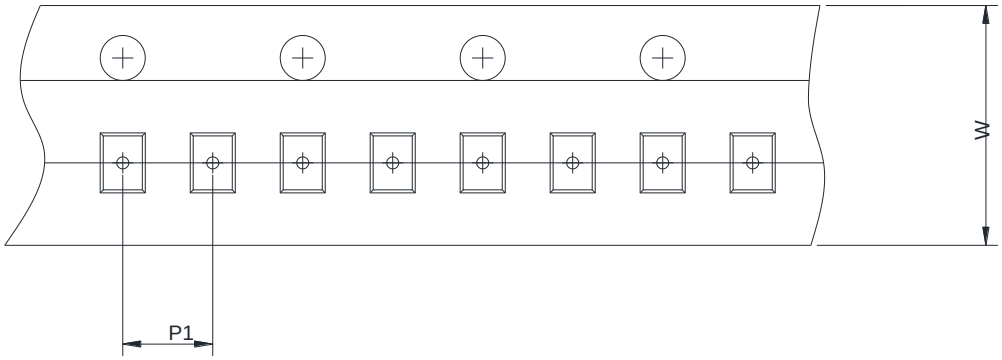
Reel Dimensions

TAPE AND REEL INFORMATION

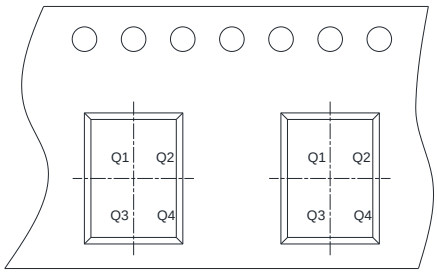
Reel Dimensions



Tape Dimensions



Quadrant Assignments For PIN1 Orientation In Tape



User Direction of Feed

RD	Reel Dimension	☑ 7inch	☐ 13inch		
W	Overall width of the carrier tape	☑ 8mm	☐ 12mm	☐ 16mm	
P1	Pitch between successive cavity centers	☑ 2mm	☐ 4mm	☐ 8mm	
Pin1	Pin1 Quadrant	☑ Q1	☐ Q2	☐ Q3	☐ Q4